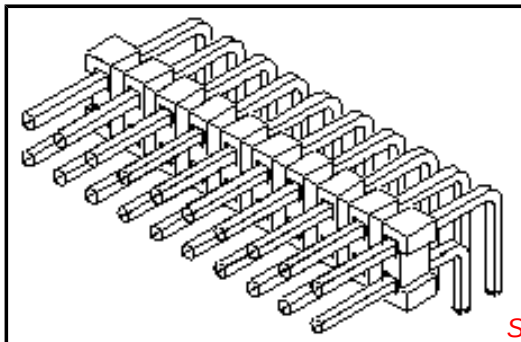
This document was generated on 03/31/2010

**PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION**

**Part Number:** 0717640020

**Status:** Active

**Description:** 2.54mm (.100") Pitch C-Grid® Breakaway Header, Low Profile, Dual Row, Right Angle, High Temperature, 20 Circuits, Tin (Sn) Plating



*Series image - Reference only*

**Documents:**

3D Model
Packaging Specification (PDF)
Drawing (PDF)
Product Specification PS-71764 (PDF)
RoHS Certificate of Compliance (PDF)

## Agency Certification

| | |
|---|---|
| CSA | LR19980 |
| UL | E29179 |

## General

| | |
|---|---|
| Product Family | PCB Headers |
| Series | 71764 |
| Application | Board-to-Board, Wire-to-Board |
| Product Name | C-Grid® |

## Physical

| | |
|---|---|
| Breakaway | Yes |
| Circuits (Loaded) | 20 |
| Circuits (maximum) | 20 |
| Color - Resin | Black |
| Durability (mating cycles max) | 25 |
| Flammability | 94V-0 |
| Glow-Wire Compliant | No |
| Lock to Mating Part | None |
| Material - Metal | Brass, Phosphor Bronze |
| Material - Plating Mating | Tin |
| Material - Plating Termination | Tin |
| Material - Resin | High Temperature Thermoplastic |
| Number of Rows | 2 |
| Orientation | Right Angle |
| PC Tail Length (in) | 0.110 In |
| PC Tail Length (mm) | 2.79 mm |
| PCB Locator | No |
| PCB Retention | None |
| Packaging Type | Tube |
| Pitch - Mating Interface (in) | 0.100 In |
| Pitch - Mating Interface (mm) | 2.54 mm |
| Plating min: Mating (µin) | 150 |
| Plating min: Mating (µm) | 3.75 |
| Plating min: Termination (µin) | 150 |
| Plating min: Termination (µm) | 3.75 |
| Polarized to Mating Part | No |
| Shrouded | No |
| Stackable | Yes |
| Temperature Range - Operating | -40°C to +105°C |
| Termination Interface: Style | Through Hole |

## Electrical

| | |
|---|---|
| Current - Maximum per Contact | 3A |
| Voltage - Maximum | 250V |

## Solder Process Data

**EU RoHS**
**ELV and RoHS Compliant**
**REACH SVHC**
**Contains SVHC: No**
**Halogen-Free Status**
**Not Reviewed**

**China RoHS**

**Need more information on product environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

Please visit the Contact Us section for any non-product compliance questions.

**Search Parts in this Series**
71764Series

| | |
|---|---|
| Lead-free Process Capability | SMC & Wave Capable (TH only) |
| Process Temperature max. C | 260 |

## Material Info

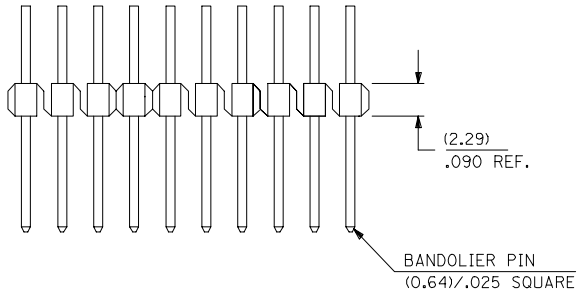
## Reference - Drawing Numbers

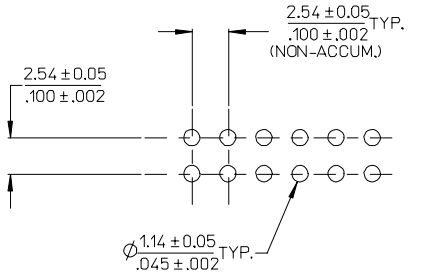
| | |
|---|---|
| Product Specification | PS-71764 |
| Sales Drawing | SD-71764-001 |

This document was generated on 03/31/2010

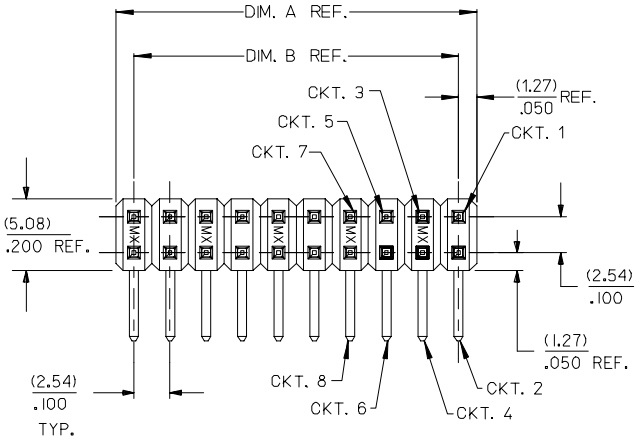
**PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION**

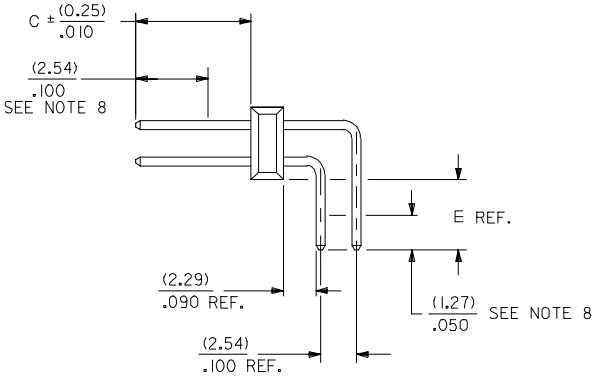
| CKTS | DIM. A | DIM. B |
|---|---|---|
| 04 | (5.08)/.200 | (2.54)/.100 |
| 06 | (7.62)/.300 | (5.08)/.200 |
| 08 | (10.16)/.400 | (7.62)/.300 |
| 10 | (12.70)/.500 | (10.16)/.400 |
| 12 | (15.24)/.600 | (12.70)/.500 |
| 14 | (17.78)/.700 | (15.24)/.600 |
| 16 | (20.32)/.800 | (17.78)/.700 |
| 18 | (22.36)/.900 | (20.32)/.800 |
| 20 | (25.40)/1.000 | (22.36)/.900 |
| 22 | (27.94)/1.100 | (25.40)/1.000 |
| 24 | (30.48)/1.200 | (27.94)/1.100 |
| 26 | (33.02)/1.300 | (30.48)/1.200 |
| 28 | (35.56)/1.400 | (33.02)/1.300 |
| 30 | (38.10)/1.500 | (35.56)/1.400 |




RECOMMENDED P.C. BOARD HOLE LAYOUT




NOTES:
1. MATERIAL: WAFER - HIGH TEMPERAURE THERMAL PLASTIC, 94V-0; COLOR: BLACK
   PIN - COPPER ALLOY
2. PLATING:
   TIN - (0.00381)/.000150 MINIMUM TIN PLATE
   OVER NICKEL PLATE.
   15 GOLD - (0.00038)/.000015 MINIMUM GOLD PLATE IN SELECT AREA,
   (0.00191)/.000075 MINIMUM TIN PLATE IN SELECT AREA,
   OVER NICKEL PLATE OVERALL.
   30 GOLD - (0.00076)/.000030 MINIMUM GOLD PLATE IN SELECT AREA,
   (0.00191)/.000075 MINIMUM TIN PLATE IN SELECT AREA,
   OVER NICKEL PLATE OVERALL.
   * THE PRIMARY SHPPING CARTON WILL BE LABELD 'COMPLIANT TO
   RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC'.
   CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.
3. PRODUCT CONFORMS TO PS-71764.
4. PACKAGING INFORMATION:
   FOR 4 THRU 8 CIRCUIT PARTS USE PK-70873-0353
   FOR 10 CIRCUITS AND OVER USE PK-70873-0075
5. FOR ILLUSTRATION PURPOSES, 20 (DUAL 10) CIRCUIT SIZE IS SHOWN.
6. PINS MUST MEET SOLDERABILITY SPEC. ES-152, EXCEPT VOIDS ARE
   PERMISSIBLE AT BANDOLIER PIN AT BANDOLIER PIN FAYING SURFACE.
   (APPROX. (0.64)/.025 LNG X (0.15)/.006 WD. REF.) 2 LOCATIONS
7. WAFER TO BE FLAT WITHIN (0.03 MM/CM) OR .003 IN./IN
8. MEASURE POINT FOR PLATING THICKNESS.
9. THIS PART CONFORMS TO CLASS B REQUIREMENTS
   OF COSMETIC SPECIFICATION PS-45499-002

| 2 | A |
|---|---|
| 1 | A1 |
| SHT. | REV. |

ADD NOTE 9 2006/12/11
EC NO: UCP2007-1441 2006/12/11
DRWN:PRIDDER CHKD:ADERR 2006/12/12
APPR:FSMITH DESCRIPTION
REV A1

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

| | mm | INCH |
|---|---|---|
| 4 PLACES | ± --- | ± --- |
| 3 PLACES | ± --- | ± .01 |
| 2 PLACES | ± 0.25 | ± .01 |
| 1 PLACE | ± 0.25 | ± --- |

ANGULAR ±1/2°

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM/IN
SCALE: 4:1
DESIGN UNITS: INCH
THIRD ANGLE PROJECTION

DRAWN BY: CAC DATE: 1995/08/23
CHECKED BY: PR DATE: 1995/08/23
APPROVED BY: DJB DATE: 1995/08/23

TITLE: DUAL ROW WAFER ASS'Y W/BREAK-OFF OPTION RT. ANG. (0.64)/.025 SQ PINS

molex MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-71764-001
SHEET NO.: 1 OF *

SIZE C

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

| ITEM NO: 71764-0004/0030, 9003 | | |
|---|---|---|
| DIM. C | (6.10)/.240 | |
| DIM. E (REF.) | (2.79)/.110 | |
| FINISH | TIN | |
| CONNECTOR END PLATING | TIN | |
| P.C. BOARD END PLATING | TIN | |
| PACKAGING | SEE NOTE 4 SHEET 1 | |
| CKTS | ITEM NUMBER | VOIDS |
| 04 | 71764-0004 | |
| 06 | 71764-0006 | |
| 08 | 71764-0008 | |
| 10 | 71764-0010 | |
| 12 | 71764-0012 | |
| 14 | 71764-0014 | |
| 16 | 71764-0016 | |
| 18 | 71764-0018 | |
| 20 | 71764-0020 | |
| 22 | 71764-0022 | |
| 24 | 71764-0024 | |
| 26 | 71764-0026 | |
| 28 | 71764-0028 | |
| 30 | 71764-0030 | |
| | | |
| 06 | 71764-9003 | 3 |
| | | |
| | | |

| ITEM NO: 71764-0104/0130, 9001, 9004 | | |
|---|---|---|
| DIM. C | (6.10)/.240 | |
| DIM. E (REF.) | (2.79)/.110 | |
| FINISH | 15 GOLD | |
| CONNECTOR END PLATING | GOLD | |
| P.C. BOARD END PLATING | TIN | |
| PACKAGING | SEE NOTE 4 SHEET 1 | |
| CKTS | ITEM NUMBER | VOIDS |
| 04 | 71764-0104 | |
| 06 | 71764-0106 | |
| 08 | 71764-0108 | |
| 10 | 71764-0110 | |
| 12 | 71764-0112 | |
| 14 | 71764-0114 | |
| 16 | 71764-0116 | |
| 18 | 71764-0118 | |
| 20 | 71764-0120 | |
| 22 | 71764-0122 | |
| 24 | 71764-0124 | |
| 26 | 71764-0126 | |
| 28 | 71764-0128 | |
| 30 | 71764-0130 | |
| | | |
| 06 | 71764-9001 | 3, 4 |
| 08 | 71764-9004 | 5, 6 |
| | | |

| ITEM NO: 71764-0204/0230, 9000, 9002 | | |
|---|---|---|
| DIM. C | (6.10)/.240 | |
| DIM. E (REF.) | (2.79)/.110 | |
| PLATING FINISH | 30 GOLD | |
| CONNECTOR END PLATING | GOLD | |
| P.C. BOARD END PLATING | TIN | |
| PACKAGING | SEE NOTE 4 SHEET 1 | |
| CKTS | ITEM NUMBER | VOIDS |
| 04 | 71764-0204 | |
| 06 | 71764-0206 | |
| 08 | 71764-0208 | |
| 10 | 71764-0210 | |
| 12 | 71764-0212 | |
| 14 | 71764-0214 | |
| 16 | 71764-0216 | |
| 18 | 71764-0218 | |
| 20 | 71764-0220 | |
| 22 | 71764-0222 | |
| 24 | 71764-0224 | |
| 26 | 71764-0226 | |
| 28 | 71764-0228 | |
| 30 | 71764-0230 | |
| | | |
| 06 | 71764-9002 | 3, 4 |
| | | |
| 10 | 71764-9000 | 8 |

| REV: | ECR/ECN INFORMATION | TITLE: | SHEET No. |
|---|---|---|---|
| **A** | EC No: **UCP2007-0449**<br>DATE: **2006-08-18** | DUAL ROW WAFER ASS'Y<br>W/ BREAK-OFF OPTION RT.<br>ANG. (0.64)/.025 SQ PINS | **- 2 -** |

| DOCUMENT NUMBER: | CREATED / REVISED BY: | CHECKED BY: | APPROVED BY: |
|---|---|---|---|
| **SD-71764-001** | **PRIDDER** | **ADERR** | **FSMITH** |

| ITEM NO: 71764-0304/0330 | | |
|---|---|---|
| DIM. C | (8.13)/.320 | |
| DIM. E (REF.) | (2.79)/.110 | |
| PLATING FINISH | TIN | |
| CONNECTOR END PLATING | TIN | |
| P.C. BOARD END PLATING | TIN | |
| PACKAGING | SEE NOTE 4 SHEET 1 | |
| CKTS | ITEM NUMBER | VOIDS |
| 04 | 71764-0304 | |
| 06 | 71764-0306 | |
| 08 | 71764-0308 | |
| 10 | 71764-0310 | |
| 12 | 71764-0312 | |
| 14 | 71764-0314 | |
| 16 | 71764-0316 | |
| 18 | 71764-0318 | |
| 20 | 71764-0320 | |
| 22 | 71764-0322 | |
| 24 | 71764-0324 | |
| 26 | 71764-0326 | |
| 28 | 71764-0328 | |
| 30 | 71764-0330 | |

| ITEM NO: 71764-0404/0430 | | |
|---|---|---|
| DIM. C | (8.13)/.320 | |
| DIM. E (REF.) | (2.79)/.110 | |
| PLATING FINISH | 15 GOLD | |
| CONNECTOR END PLATING | GOLD | |
| P.C. BOARD END PLATING | TIN | |
| PACKAGING | SEE NOTE 4 SHEET 1 | |
| CKTS | ITEM NUMBER | VOIDS |
| 04 | 71764-0404 | |
| 06 | 71764-0406 | |
| 08 | 71764-0408 | |
| 10 | 71764-0410 | |
| 12 | 71764-0412 | |
| 14 | 71764-0414 | |
| 16 | 71764-0416 | |
| 18 | 71764-0418 | |
| 20 | 71764-0420 | |
| 22 | 71764-0422 | |
| 24 | 71764-0424 | |
| 26 | 71764-0426 | |
| 28 | 71764-0428 | |
| 30 | 71764-0430 | |

| ITEM NO: 71764-0504/0530 | | |
|---|---|---|
| DIM. C | (8.13)/.320 | |
| DIM. E (REF.) | (2.79)/.110 | |
| PLATING FINISH | 30 GOLD | |
| CONNECTOR END PLATING | GOLD | |
| P.C. BOARD END PLATING | TIN | |
| PACKAGING | SEE NOTE 4 SHEET 1 | |
| CKTS | ITEM NUMBER | VOIDS |
| 04 | 71764-0504 | |
| 06 | 71764-0506 | |
| 08 | 71764-0508 | |
| 10 | 71764-0510 | |
| 12 | 71764-0512 | |
| 14 | 71764-0514 | |
| 16 | 71764-0516 | |
| 18 | 71764-0518 | |
| 20 | 71764-0520 | |
| 22 | 71764-0522 | |
| 24 | 71764-0524 | |
| 26 | 71764-0526 | |
| 28 | 71764-0528 | |
| 30 | 71764-0530 | |

| REV: | ECR/ECN INFORMATION | TITLE: | SHEET No. |
|---|---|---|---|
| **A** | EC No: **UCP2007-0449**<br>DATE: **2006-08-18** | DUAL ROW WAFER ASS'Y<br>W/ BREAK-OFF OPTION RT.<br>ANG. (0.64)/.025 SQ PINS | **- 3 -** |

| DOCUMENT NUMBER: | CREATED / REVISED BY: | CHECKED BY: | APPROVED BY: |
|---|---|---|---|
| **SD-71764-001** | **PRIDDER** | **ADERR** | **FSMITH** |